



## TOSCA ADSL DMT TRANSCEIVER

PRODUCT PREVIEW

- ANSI T1.413 issue 2 standard DMT modem
- Same chip for both ATU-C and ATU-R
- Supports either ATM (Utopia level 1 & 2) or STM streams
- 16 bit multiplexed microprocessor interface (little and big endian compatibility)
- Analog Front End management
- 144 pin PQFP package
- Power Consumption 1 Watt at 3.3V
- Dual latency paths: fast and interleaved
- ATM's PHY layer: cell processing (cell delineation, cell insertion, HEC)
- ADSL's overhead management
- Reed Solomon encode/decode
- Trellis encode/decode (Viterbi)
- DMT mapping/ demapping over 256 carriers
- Fine (2ppm) timing recover using Rotor and Adaptive Frequency Domain Equalizing
- Time Domain Equalization
- Front end digital filters

### Applications

- **ATU-C:** DSLAM, Routers at Central Office
- **ATU-R:** Routers at SOHO, stand-alone modems, PC mother boards



### General Description

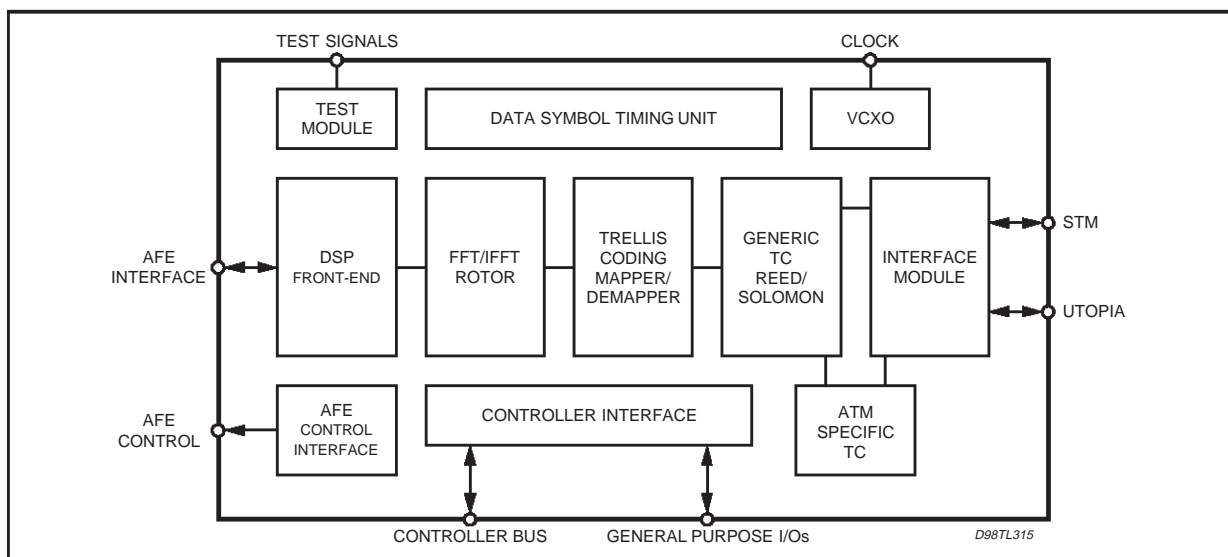
The STLC60135 is the DMT modem and ATM framer of TOSCA chipset.

When coupled with STLC60134 analog front-end and an external controller running dedicated firmware, the product fulfils ANSI T1.413 "Issue 2" DMT ADSL specification.

The STLC60135 may be used at both ends of ADSL loop: ATU-C and ATU-R. The chip supports UTOPIA level 1 and UTOPIA level 2 interface and a non ATM synchronous bit-stream interface.

The STLC60135 can be splitted up into two different sections. The physical one performs the DMT modulation, demodulation, Reed-Solomon encoding, bit interleaving and 4D trellis coding.

Figure 1. Block Diagram



# STLC60135

The ATM section embodies framing functions for the generic and ATM Transmission Convergence (TC) layers. The generic TC consists of data scrambling and Reed Solomon error corrections, with and without interleaving. The STLC60135 is controlled and programmed by external controller (ADSL Transceiver Controller, ATC) that sets the programmable coefficients. The firmware controls the initialization phase and carries out the consequent adaptation operations.

## Transient Energy Capabilities

### ESD

ESD (Electronic Discharged) tests have been performed for the Human Body Model (HBM) and for the Charged Device Model (CDM).

The pins of the device are to be able to withstand minimum 1500V for the HBM and minimum 250V for CDM.

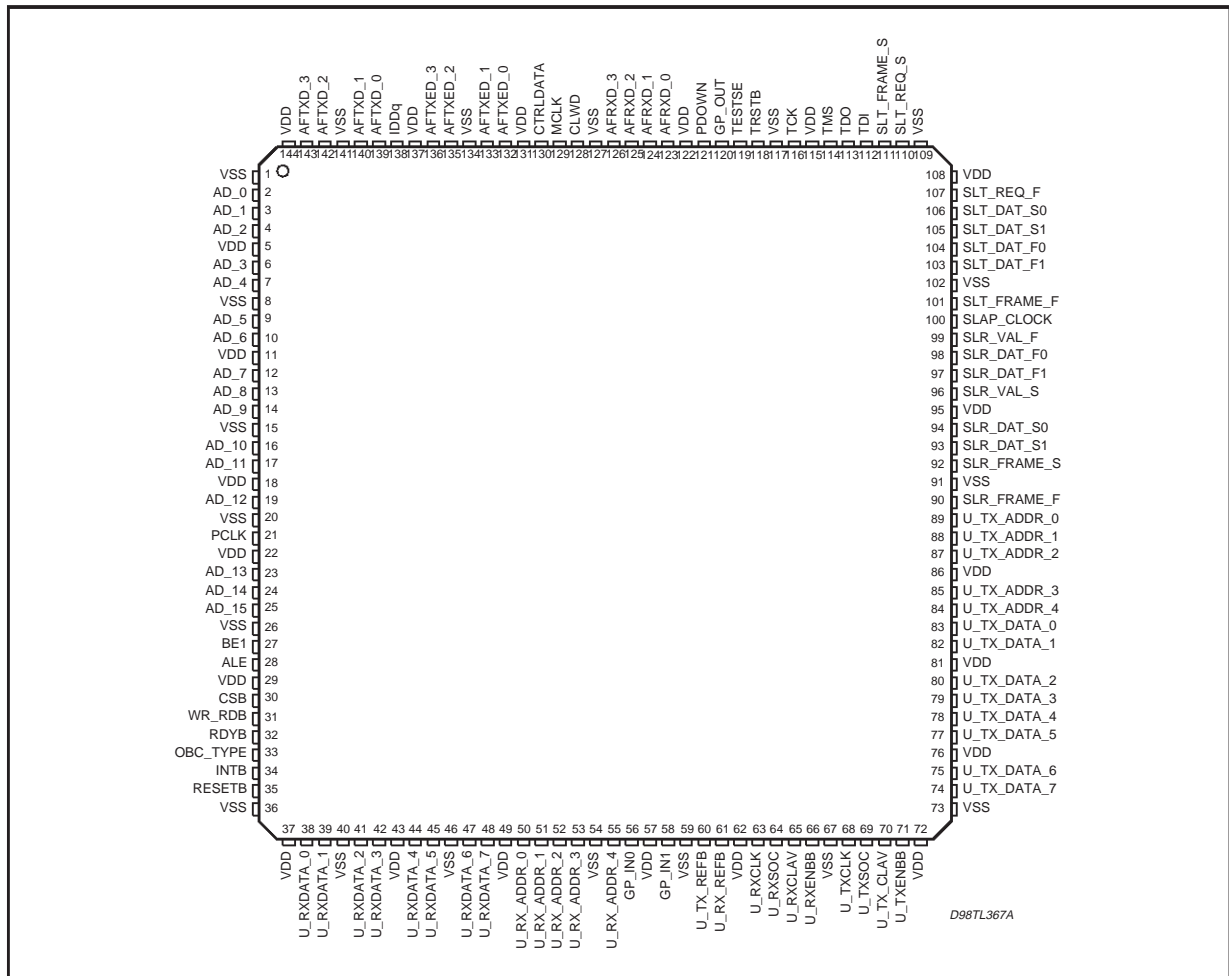
### Latch-up

The maximum sink or source current from any pin is limited to 100mA to prevent latch-up.

## ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Min	Typ	Max	Unit
V <sub>DD</sub>	Supply Voltage	3.0	3.3	3.6	V
P <sub>tot</sub>	Total Power Dissipation		900	1400	mW
T <sub>amb</sub>	Ambient Temperature 1m/s airflow	-40		85	°C

Figure 2. Pin Connection



## PIN FUNCTIONS

Pin	Name	Type	Supply	Driver	BS	Function
1	VSS					0V Ground
2	AD_0	B	VDD	BD8SCR	B	Data 0
3	AD_1	B	VDD	BD8SCR	B	Data 1
4	AD_2	B	VDD	BD8SCR	B	Address / Data 2
5	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
6	AD_3	B	VDD	BD8SCR	B	Address / Data 3
7	AD_4	B	VDD	BD8SCR	B	Address / Data 4
8	VSS					0V Ground
9	AD_5	B	VDD	BD8SCR	B	Address / Data 5
10	AD_6	B	VDD	BD8SCR	B	Address / Data 6
11	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
12	AD_7	B	VDD	BD8SCR	B	Address / Data 7
13	AD_8	B	VDD	BD8SCR	B	Address / Data 8
14	AD_9	B	VDD	BD8SCR	B	Address / Data 9
15	VSS					0V Ground
16	AD_10	B	VDD	BD8SCR	B	Address / Data 10
17	AD_11	B	VDD	BD8SCR	B	Address / Data 11
18	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
19	AD_12	B	VDD	BD8SCR	B	Address / Data 12
20	VSS					0V Ground
21	PCLK	I	VDD	IBUF	I	Processor clock
22	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
23	AD_13	B	VDD	BD8SCR	B	Address / Data 13
24	AD_14	B	VDD	BD8SCR	B	Address / Data 14
25	AD_15	B	VDD	BD8SCR	B	Address / Data 15
26	VSS					0V Ground
27	BE1	I	VDD	IBUF	I	Address 1
28	ALE	I	VDD	IBUF	C	Address Latch
29	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
30	CSB	I	VDD	IBUF	I	Chip Select
31	WR_RDB	I	VDD	IBUF	I	Specifies the direction of the access cycle
32	RDYB	OZ	VDD	BT4CR	O	Controls the ATC bus cycle termination
33	OBC_TYPE	I-PD	VDD	IBUF	I	ATC Mode Selection (0 = i960; 1 = generic)
34	INTB	O	VDD	IBUF	O	Requests ATC interrupt service
35	RESETB	I	VDD	IBUF	I	Hard reset
36	VSS					0V Ground
37	VDD					(V <sub>SS</sub> + 3.3V) Power Supply
38	U_RxData_0	OZ	VDD	BD8SRC	B	Utopia RX Data 0
39	U_RxData_1	OZ	VDD	BD8SRC	B	Utopia RX Data 1
40	VSS					0V Ground
41	U_RxData_2	OZ	VDD	BD8SRC	B	Utopia RX Data 2
42	U_RxData_3	OZ	VDD	BD8SRC	B	Utopia RX Data 3
43	VDD					(V <sub>SS</sub> + 3.3V) Power Supply

## PIN FUNCTIONS (continued)

Pin	Name	Type	Supply	Driver	BS	Function
44	U_RxData_4	OZ	VDD	BD8SRC	B	Utopia RX Data 4
45	U_RxData_5	OZ	VDD	BD8SRC	B	Utopia RX Data 5
46	VSS					0V Ground
47	U_RxData_6	OZ	VDD	BD8SRC	B	Utopia RX Data 6
48	U_RxData_7	OZ	VDD	BD8SRC	B	Utopia RX Data 7
49	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
50	U_RxADDR_0	I	VDD	IBUF	I	Utopia RX Address 0
51	U_RxADDR_1	I	VDD	IBUF	I	Utopia RX Address 1
52	U_RxADDR_2	I	VDD	IBUF	I	Utopia RX Address 2
53	U_RxADDR_3	I	VDD	IBUF	I	Utopia RX Address 3
54	VSS					0V Ground
55	U_RxADDR_4	I	VDD	IBUF	I	Utopia RX Address 4
56	GP_IN_0	I-PD	VDD	IBUFDQ	I	General purpose input 0
57	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
58	GP_IN_1	I-PD	VDD	IBUFDQ	I	General purpose input 1
59	VSS					0V Ground
60	U_RxRefB	O	VDD	IBUF	O	8kHz clock to ATM device
61	U_TxRefB	I	VDD	BT4CR	I	8kHz clock from ATM device
62	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
63	U_Rx_CLK	I	VDD	IBUF		Utopia RX Clock
64	U_Rx_SOC	OZ	VDD	BD8SCR		Utopia RX Start of Cell
65	U_RxCLAV	OZ	VDD	BD8SCR		Utopia RX Cell Available
66	U_RxENBB	I	VDD	IBUF		Utopia RX Enable
67	VSS					0V Ground
68	U_Tx_CLK	I	VDD	IBUF		Utopia TX Clock
69	U_Tx_SOC	I	VDD	IBUF		Utopia TX Start of Cell
70	U_TxCLAV	OZ	VDD	BD8SCR		Utopia TX Cell Available
71	U_TxENBB	I	VDD	IBUF		Utopia TX Enable
72	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
73	VSS					0V Ground
74	U_TxData_7	I	VDD	IBUF	I	Utopia TX Data 7
75	U_TxData_6	I	VDD	IBUF	I	Utopia TX Data 6
76	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
77	U_TxData_5	I	VDD	IBUF	I	Utopia TX Data 5
78	U_TxData_4	I	VDD	IBUF	I	Utopia TX Data 4
79	U_TxData_3	I	VDD	IBUF	I	Utopia TX Data 3
80	U_TxData_2	I	VDD	IBUF	I	Utopia TX Data 2
81	VSS					0V Ground
82	U_TxData_1	I	VDD	IBUF	I	Utopia TX Data 1
83	U_TxData_0	I	VDD	IBUF	I	Utopia TX Data 0
84	U_TxADDR_4	I	VDD	IBUF	I	Utopia TX Address 4
85	U_TxADDR_3	I	VDD	IBUF	I	Utopia TX Address 3
86	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
87	U_TxADDR_2	I	VDD	IBUF	I	Utopia TX Address 2
88	U_TxADDR_1	I	VDD	IBUF	I	Utopia TX Address 1
89	U_TxADDR_0	I	VDD	IBUF	I	Utopia TX Address 0
90	SLR_FRAME_F	O	VDD	BT4CR		Frame Identifier Fast
91	VSS					0V Ground

## PIN FUNCTIONS (continued)

Pin	Name	Type	Supply	Driver	BS	Function
92	SLR_FRAME_S	O	VDD	BT4CR		Frame Identifier Interleaved
93	SLR_DATA_S_1	O	VDD	BT4CR		Data Interleave 1
94	SLR_DATA_S_0	O	VDD	BT4CR		Data Interleave 0
95	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
96	SLR_VAL_S	O	VDD	BT4CR		Data Valid Indicator Interleaved
97	SLR_DATA_F_1	O	VDD	BT4CR		Data Fast 1
98	SLR_DATA_F_0	O	VDD	BT4CR		Data Fast 0
99	SLR_VAL_F	O	VDD	BT4CR		Data Valid Indicator Fast
100	SLAP_CLOK	O	VDD	BT4CR		Clock for SLAP I/F
101	SLT_FRAME_F	O	VDD	BT4CR		Start of frame Indicator Fast
102	VSS					0V Ground
103	SLT_DATA_F_1	I	VDD	IBUFDQ		Fast Data 1
104	SLT_DATA_F_0	I	VDD	IBUFDQ		Fast Data 0
105	SLT_DATA_S_1	I	VDD	IBUFDQ		Data 1
106	SLT_DATA_S_0	I	VDD	IBUFDQ		Data 0
107	SLT_REQ_F	O	VDD	BT4CR		Byte Request Fast
108	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
109	VSS					0V Ground
110	SLT_REQ_S	O	VDD	BT4CR		Byte Request Interleaved
111	STL_FRAME_S	O	VDD	BT4CR		Start of frame Indication Interleaved
112	TDI	I-PU	VDD	IBUFUQ		JTAG I/P
113	TDO	OZ	VDD	BT4CR		JTAG O/P
114	TMS	I-PU	VDD	IBUFUQ		JTAG Mode Select
115	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
116	TCK	I-PD	VDD	IBUFDQ		JTAG Clock
117	VSS					0V Ground
118	TRSTB	I-PD	VDD	IBUFDQ		JTAG Reset
119	TESTSE	I	VDD	IBUF	none	Enables scan test mode
120	GP_OUT	O	VDD	BD8SCR	O	General purpose output
121	PDOWN	O	VDD	BT4CR	O	Power down analog front end
122	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
123	AFRXD_0	I	VDD	IBUF	I	Receive data nibble
124	AFRXD_1	I	VDD	IBUF	I	Receive data nibble
125	AFRXD_2	I	VDD	IBUF	I	Receive data nibble
126	AFRXD_3	I	VDD	IBUF	I	Receive data nibble
127	VSS					0V Ground
128	CLWD	I	VDD	IBUF	I	Start of word indication
129	MCLK	I	VDD	IBUF	C	Master clock
130	CTRLDATA	O	VDD	BT4CR	O	Serial data Transmit channel
131	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
132	AFTXED_0	O	VDD	BT4CR	O	Transmit echo nibble
133	AFTXED_1	O	VDD	BT4CR	O	Transmit echo nibble
134	VSS					0V Ground
135	AFTXED_2	O	VDD	BT4CR	O	Transmit echo nibble
136	AFTXED_3	O	VDD	BT4CR	O	Transmit echo nibble
137	VDD					(V <sub>ss</sub> + 3.3V) Power Supply
138	IDDq	I	VDD	IBUF	none	Test pin, active high

## STLC60135

### PIN FUNCTIONS (continued)

Pin	Name	Type	Supply	Driver	BS	Function
139	AFTXD_0	O	VDD	BT4CR	O	Transmit data nibble
140	AFTXD_1	O	VDD	BT4CR	O	Transmit data nibble
141	VSS					0V Ground
142	AFTXD_2	O	VDD	BT4CR	O	Transmit data nibble
143	AFTXD_3	O	VDD	BT4CR	O	Transmit data nibble
144	VDD					(V <sub>ss</sub> + 3.3V) Power Supply

### I/O DRIVER FUNCTION

Driver	Function
BD4CR	CMOS bidirectional, 4mA, slew rate control
BD8SCR	CMOS bidirectional, 8mA, slew rate control, Schmitt trigger
IBUF	CMOS input
IBUFDQ	CMOS input, pull down, IDDq control
IBUFUQ	CMOS input, pull up, IDDq control

### PIN SUMMARY

Mnemonic	Type	BS Type	Signals	Function
<b>Power Supply</b>				
VDD				(V <sub>ss</sub> + 3.3V) Power Supply
VSS				0V Ground
<b>ATC Interface</b>				
ALE	I	C	1	Used to latch the address of the internal register to be accessed
PCLK	I	I	1	Processor clock
CSB	I	I	1	Chip selected to respond to bus cycle
BE1	I	I	1	Address 1 (not multiplexed)
WR_RDB	I	I	1	Specifies the direction of the access cycle
RDYB	OZ	O	1	Controls the ATC bus cycle termination
INTB	O	O	1	Requests ATC interrupt service
AD	IO	B	16	Multiplexed Address/Data bus
OBC_TYPE	I-PD	I	1	Select between i960 (0) or generic (1) controller interface
<b>Test Access Part Interface</b>				
TDI	I-PU		1	refer to section
TDO	OZ		1	
TCK	I-PD		1	
TMS	I-PU		1	
TRSTB	I-PD		1	
<b>Analog Front End Interface</b>				
AFRXD	I	I	4	Receive data nibble
AFTXD	O	O	4	Transmit data nibble
AFTXED	O	O	4	Transmit echo nibble
CLWD	I	I	1	Start of word indication
PDOWN	O	O	1	Power down analog front end
CTRLDATA	O	O	1	Serial data transmit channel
MCLK	I	C	1	Master clock

## PIN SUMMARY (continued)

Mnemonic	Type	BS Type	Signals	Function
<b>ATM UTOPIA Interface</b>				
U_RxData	OZ	B	8	Receive interface Data
U_TxData	I	I	8	Transmit interface Data
U_RxADDR	I	I	5	Receive interface Address
U_TxADDR	I	I	5	Transmit interface Address
U_RxCLAV	OZ	O	1	Receive interface Cell Available
U_TxCLAV	OZ	O	1	Transmit interface Cell Available
U_RxENBB	I-TTL	I	1	Receive interface Enable
U_TxENBB	I-TTL	I	1	Transmit interface Enable
U_RxSOC	OZ	O	1	Receive interface Start of Cell
U_TxSOC	I-TTL	I	1	Transmit interface Start of Cell
U_RxCLK	I-TTL	C	1	Receive interface Utopia Clock
U_TxCLK	I-TTL	C	1	Transmit interface Utopia Clock
U_RxRefB	O	O	1	8kHz reference clock to ATM device
U_TxRefB	I-TTL	I	1	8kHz reference clock from ATM device
<b>ATM SLAP Interface</b>				
SLR_VAL_S	O		1	
SLR_VAL_F	O		1	
SLR_DATA_S	O		2	
SLR_DATA_F	O		2	
SLT_REQ_S	O		1	
SLT_REQ_F	O		1	
SLT_DATA_S	I		2	
SLT_DATA_F	I		2	
SLAP_CLOCK	O		1	
SLR_FRAME_I	O		1	
SLT_FRAME_I	O		1	
SLR_FRAME_F	O		1	
SLT_FRAME_F	O		1	
<b>Miscellaneous</b>				
GP_IN	I-PD	I	2	General purpose input
GP_OUT	O	O	1	General purpose output
RESETB	I	I	1	Hard reset
TESTSE	I	none	none	Enable scan test mode
IDDq	I	none	none	Test pin, active high

I	=	Input, CMOS levels
I-PU	=	Input with pull-up resistance, CMOS levels
I-PD	=	Input with pull-down resistance, CMOS levels
I-TTL	=	Input TTL levels
O	=	Push-pull output
OZ	=	Push-pull output with high-impedance state
IO	=	Input / Tristate Push-pull output
BS cell	=	Boundary-Scan cell
I	=	Input cell
O	=	Output cell
B	=	Bidirectional cell
C	=	Clock

**Main Block Description**

The following drawings describe the sequence of actions performed by the chip.

**DSP Front-End**

The DSP Front-End contains 4 parts in the receive direction: the Input Selector, the Analog Front-End Interface, the Decimator and the Time Equalizer. The input selector is used internally to enable test loopbacks inside the chip. The Analog Front-End Interface transfers 16-bit words, multiplexed on 4 input/output signals. Word transfer is carried out in 4 clock cycles.

The Decimator receive 16-bits samples at 8.8 MHz (as sent by the Analog Front-End chip: STLC60134) and reduces this rate to 2.2 MHz.

The Time Equalizer (TEQ) module is a FIR filter with programmable coefficients. Its main purpose is to reduce the effect of Inter-Symbol Interferences (ISI) by shortening the channel impulse response.

Both the Decimator and TEQ can be bypassed.

In the transmit direction, the DSP Front-End includes: sidelobe filtering, clipping, delay equalization and interpolation. The sidelobe filtering and

delay equalization are implemented by IIR Filters, reducing the effect of echo in FDM systems. Clipping is a statistical process limiting the amplitude of the output signal, optimizing the dynamic range of the AFE. The interpolator receives data at 2.2 MHz and generates samples at a rate of 8.8 MHz.

**DMT Modem**

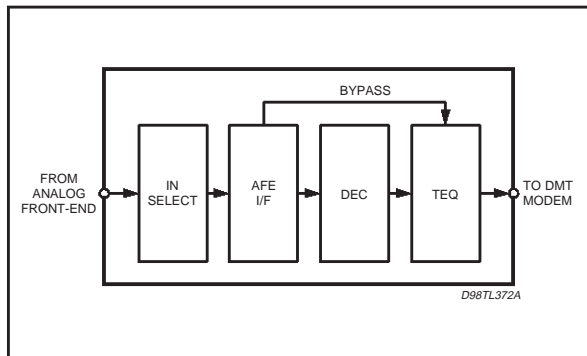
This module is a programmable DSP unit. Its instruction set enables the basic functions of the DMT algorithm like FFT, IFFT, Scaling, Rotor and Frequency Equalization (FEQ) in compliance with ANSI T1.413 specifications.

In the RX path, the 512-point FFT transforms the time-domain DMT symbol into a frequency domain representation which can be further decoded by the subsequent demapping stages.

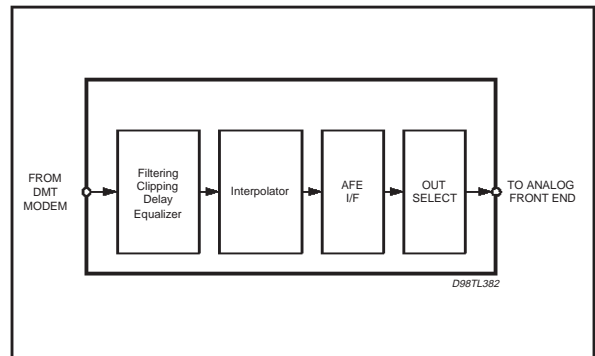
In other words, the Fast Fourier Transform process is used to transform from time domain to frequency domain (receive path). On ATU-C side, 128 time samples are processed. On ATU-R side, 1024 time samples are processed.

After the first stage time domain equalization and FFT block an ICI (InterCarrier Interference) free information stream turns out.

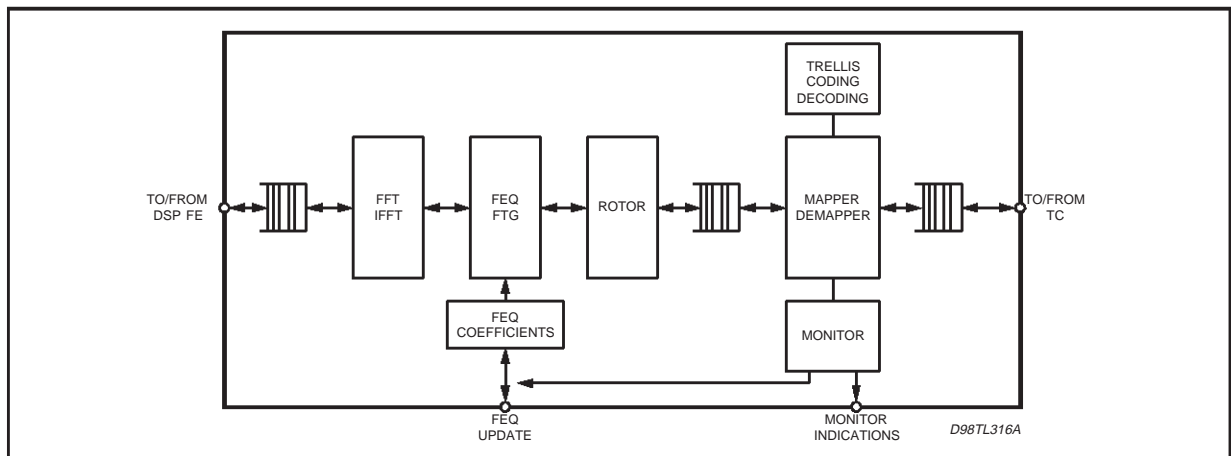
**Figure 3. DSP Front-End Receive**



**Figure 4. DSP Front-End Transmit**



**Figure 5. DMT Modem**





This stream is still affected by carrier specific channel distortion resulting in an attenuation of the signal amplitude and a rotation of the signal phase. To compensate, a Frequency domain equalizer (FEQ) and a Rotor (phase shifter) are implemented. The frequency domain equalisation performs an operation on the received vector in order to match it with the associated point in the constellation. The coefficient used to perform the equalisation are floating point, and may be updated by hardware or software, using a mechanism of active and inactive table to avoid DMT synchro problems.

In the transmit path, the IFFT reverses the DMT symbol from frequency domain to time domain.

The IFFT block is preceded by Fine Tune Gain (FTG) and Rotor stages, allowing for a compensation of the possible frequency mismatch between the master clock frequency and the transmitter clock frequency (which may be locked to another reference).

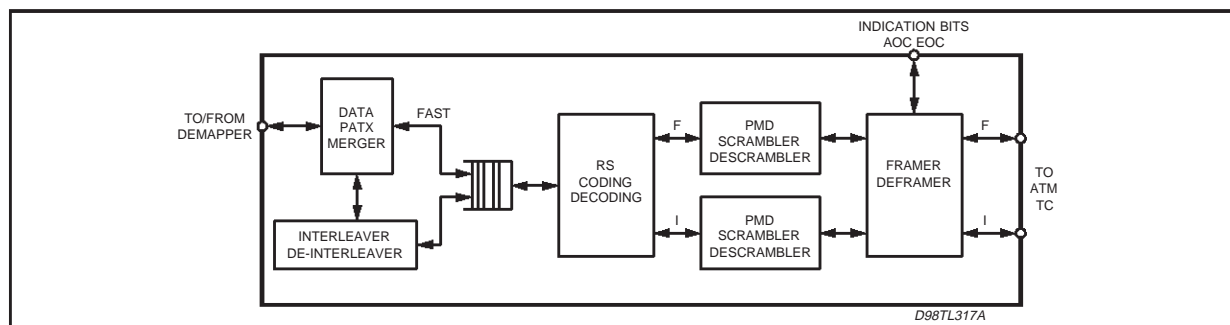
The Inverse Fast Fourier Transform process is used to transform from frequency domain to time domain (transmit path). On ATU-C side, 512 frequencies are processed, giving 1024 samples in the time domain. On ATU-R side, 256 positive frequencies are processed, giving 512 samples in the time domain.

The FFT module is a slave DSP engine controlled by the firmware running on an external controller. It works off line and communicates with other blocks through buffers controlled by the "Data Symbol Timing Unit". The DSP executes a program stored in a RAM area, which constitutes a flexible element that allows for future system enhancements.

## DPLL

The Digital PLL module receives a metric for the phase error of the pilot tone. In general, the clock frequencies at the ends (transmitter and receiver) do not match exactly. The phase error is filtered and integrated by a low pass filter, yielding an estimation of the frequency offset. Various processes can use this estimate to deal with the frequency mismatch.

**Figure 6. Generic TC Layer Functions**



In particular, small accumulated phase error can be compensated in the frequency domain by a rotation of the received code constellation (Rotor). Larger errors are compensated in the time domain by inserting or deleting clock cycles in the sample input sequence.

Eventually that leads to achieve less than 2ppm between the two ends.

## Mapper/Demapper, Monitor, Trellis Coding, FEQ Update

The Demapper converts the constellation points computed by the FFT to a block of bits. This means to identify a point in a 2D QAM constellation plane. The Demapper supports Trellis coded demodulation and provides a Viterbi maximum likelihood estimator. When the Trellis is active, the Demapper receives an indication for the most likely constellation subset to be used.

In the transmit direction, the mapper receives a bit stream from the Trellis encoder and modulates the bit stream on a set of carriers (up to 256). It generate coordinates for  $2n$  QAM constellation, where  $n < 15$  for all carriers.

The Mapper performs the inverse operation, mapping a block of bits into one constellation point (in a complex  $x+jy$  representation) which is passed to the IFFT block. The Trellis Encoder generates redundant bits to improve the robustness of the transmission, using a 4-Dimensional Trellis Coded Modulation scheme. This feature can be disabled.

The Monitor computes error parameters for carriers specified in the Demapper process. Those parameters can be used for updates of adaptive filters coefficients, clock phase adjustments, error detection, etc. A series of values is constantly monitored, such as signal power, pilot phase deviations, symbol erasures generation, loss of frame, etc.

## Generic TC Layer Functions

These functions relate to byte oriented data streams. They are completely described in ANSI T 1.4 13. Additions described in the Issue 2 of

this specification are also supported. The data received from the demapper may be split into two paths, one dedicated to an interleaved data flow the other one for a fast data flow. No external RAM is needed for the interleaved path.

The interleaving/deinterleaving is used to increase the error correcting capability of block codes for error bursts. After deinterleaving (if applicable), the data flow enters a Reed-Solomon error correcting code decoder, able to correct a number of bytes containing bit errors. The decoder also uses the information of previous receiving stages that may have detected the errored bytes and have labelled them with an "erasure" indication".

Each time the RS decoder detects and corrects errors in a RS codeword, an RS correction event is generated. The occurrence of such events can be signalled to the management layer.

After the RS decoder, the corrected byte stream is descrambled in the PMD (Physical Medium Dependent) descramblers.

Two descramblers are used, for interleaved and non-interleaved data flows.

These are defined in ANSI T1.413.

After descrambling, the data flows enter the Deframer that extracts and processes bytes to support Physical layer related functions according to ANSI T1.413. The ADSL frames indeed contain physical layer-related information in addition to the data passed to the higher layers. In particular, the deframer extracts the EOC (Embedded Operations Channel), the AOC (ADSL Overhead Control) and the indicators bits and passes them to the appropriate processing unit (e.g. the transceiver controller). The deframer also performs a CRC check (Cyclic Redundancy Check ) on the received frame and generates events in case of error detection.

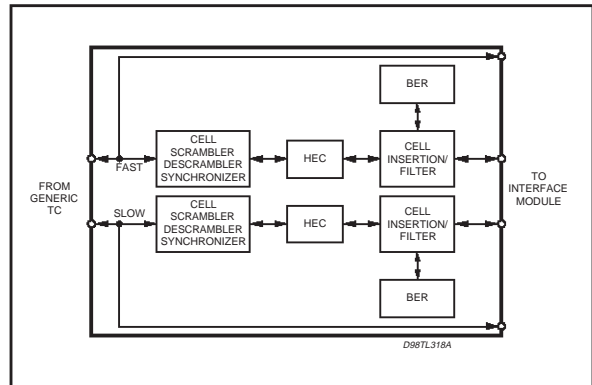
Event counters can be read by management processes. The outputs of the deframer are an interleaved and a fast data streams.

These data streams can either carry ATM cells or another type of traffic. In the latter case, the ATM specific TC layer functional block, described hereafter, is bypassed and the data stream is directly presented at the input of the interface module.

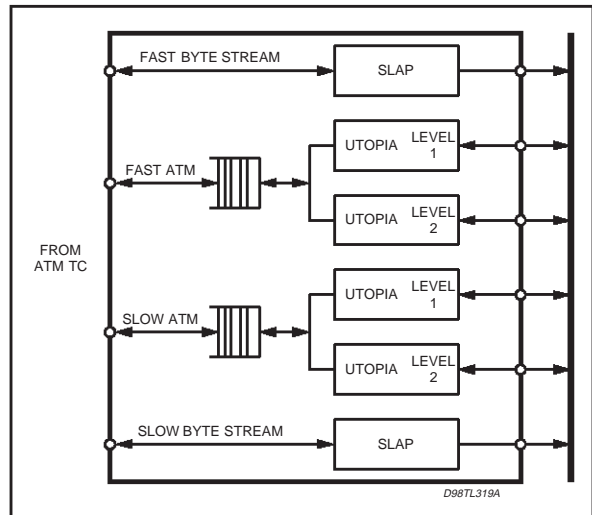
**ATM Specific TC Layer Functions**

The 2 bytes streams (fast and slow) are received from the byte-based processing unit. When ATM cells are transported, this block provides basic cell functions such as cell synchronization, cell payload descrambling, idle/unassigned cell filter, cell Header Error Correction (HEC) and detection. The cell processing happens according to ITU-T I.163 standard. Provision is also made for BER measurements at this ATM cell level. When non cell oriented byte streams are transported, the cell processing unit is not active. The interface

**Figure 7. ATM Specific TC Layer Functions**



**Figure 8. Interface Module**



module collects cells (from the cell-based function module) or a Byte stream (from the deframer). Cells are stored in FIFO's (424 bytes or 8 cell wide, transmit buffers have the same size), from which they are extracted by 2 interface sub-modules, one providing a Utopia level 1 interface and the other a Utopia level 2 interface. Byte stream are dumped on the SLAP (Synchronous Link Access Protocol) interface. Only one type of interface can be enabled in a specific configuration.

**DMT Symbol Timing Unit (DSTU)**

The DSTU interfaces with various modules, like DSP FrontEnd, FFT/IFFT, Mapper/Demapper, RS , Monitor and Transceiver Controller. It consists of a real time and a scheduler modules. The real time unit generate a timebase for the DMT symbols (sample counter), superframes (symbol counter) and hyper-frames (sync counter). The timebases can be modified by various control features. They are continuously fine-tuned by the DPLL module.

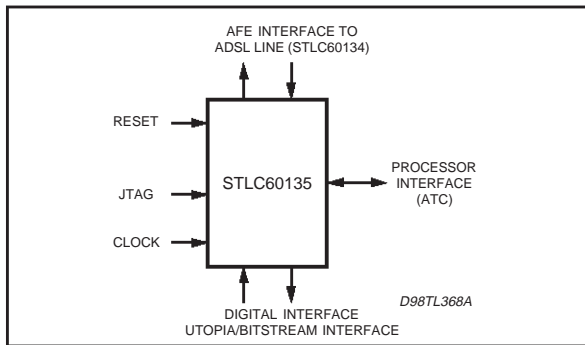


The DSTU schedulers execute a program, controlled by program opcodes and a set of variables, the most important of which are real time counters. The transmit and receive sequencers are completely independent and run different programs. An independent set of variables is assigned to each of them. The sequencer programs can be updated in real time.

**STLC60135 interfaces**

■ Overview

**Figure 9. STLC60135 interfaces**



■ Processor Interface (ATC)

The STLC60135 is controlled and configured by an external processor across the processor interface. All programmable coefficients and parameters are loaded through this path.

The ADSL initialization is also controlled by this interface

Two interface types are supported; A generic asynchronous interface (i.e. PowerPC or any microprocessor interface) and a specific i960 interface. The choice is made by the OBC\_TYPE pin. (0 selects i960 type interface, 1 selects generic access).

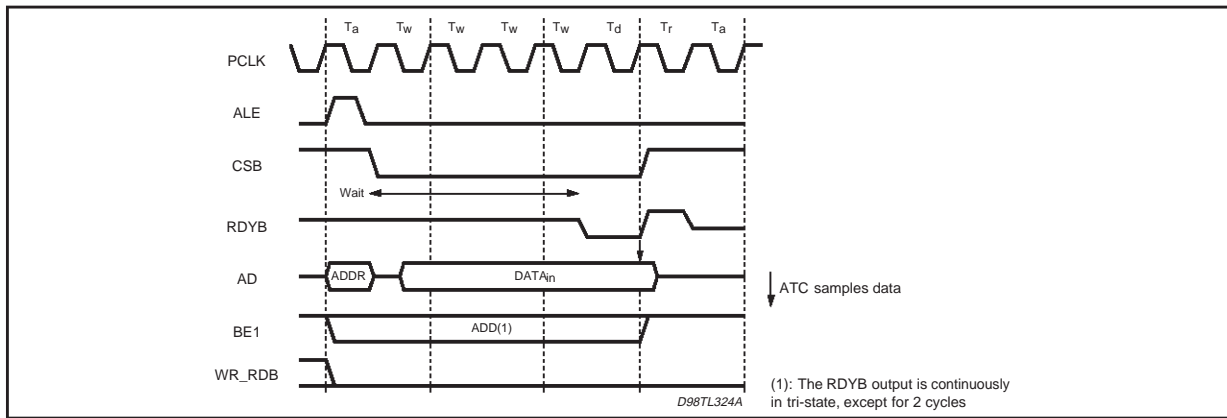
**Data and addresses are multiplexed.**

STLC60135 works in 16 bits data access, so address bit 0 is not used. Address bit 1 is not multiplexed with data. It has its own pin : BE1

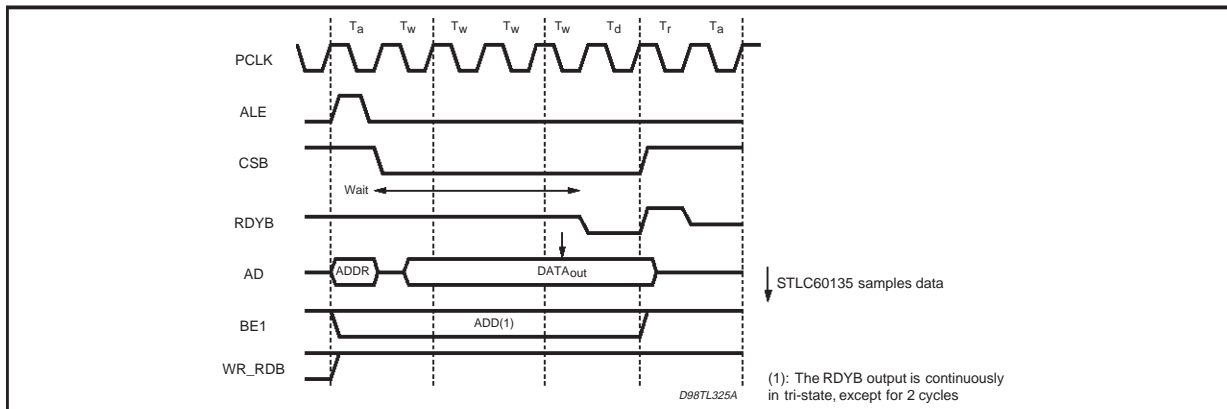
Byte access are not supported. Access cycle read or write are always in 16 bits data wide, ie bit address A0 is always zero value. The interrupt request pin to the processor is INTB, and is an Open Drain output.

The STLC60135 supports both little and big endian. The default feature is big endian.

**Figure 10. Processor Interface Read cycle i960 mode**



**Figure 11. Processor Interface Write Cycle i960 mode**



**The processor interface in i960 mode**

The i960 mode supports a synchronous bus interface protocol.

Address and data are multiplexed. The processor is bus master and the STLC60135 is bus slave. Synchronous means that all signals are synchronous with the input clock PCLK pin,

The bus cycles are directly started and driven by the processor. Addresses (BE1, AD[2..15]) have to be present before ATC asserts the ALE signal.

STLC60135 latches the address on the falling edge of ALE signal.

The RDYB output is synchronous to PCLK.

A bus cycle consists of an Access cycle ( $T_a$ ), Wait cycles ( $T_w$ ), Data cycle ( $T_d$ ) and Recovery cycle ( $T_r$ ).

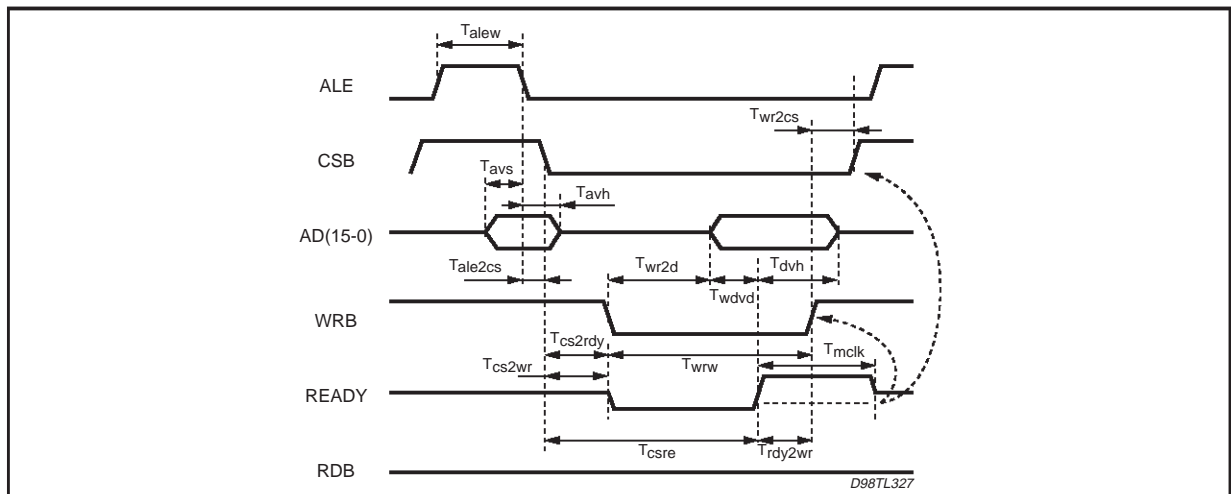
**Processor Interface Pins and Functional Description i960 mode**

Name	Type	Function
AD[0...15]	I/O	Multiplexed Address/Data bus
BE1	I	Address bit 1
ALE	I	Address Latch Enable
WR_RDB	I	Access direction: Write (1), Read (0)
PCLK	I	Processor Clock
CSB	I	Chip Select
RDYB	OZ	Bus cycle ready indication
INTB	O	Interrupt

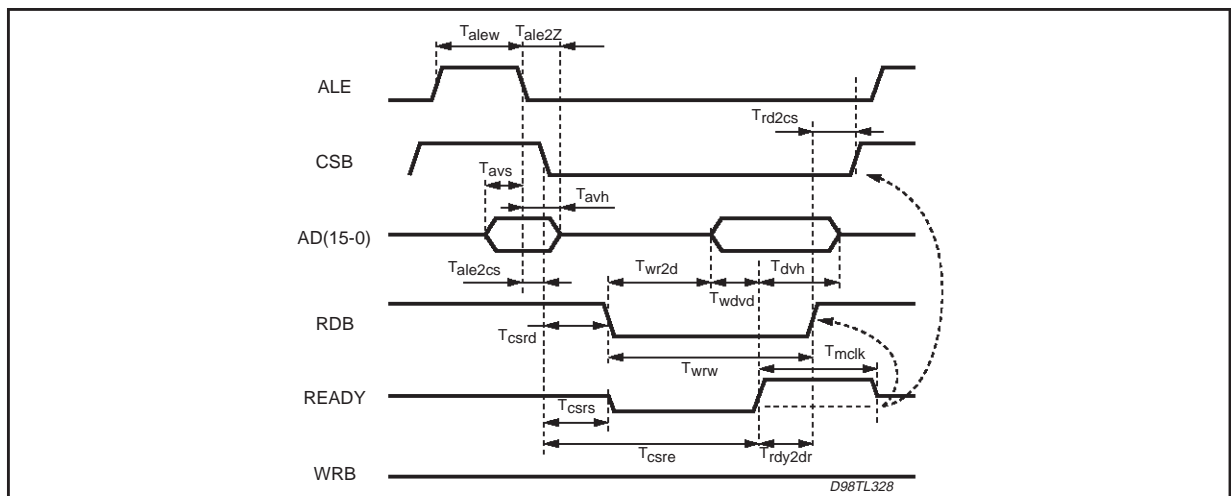
**Generic Interface**

This interface is suitable for a number of processors using a multiplexed Address/data bus. In this case, synchronisation of the input signals with PCLK pin is not necessary.

**Figure 12. Generic Processor Interface Write Timing Cycle**



**Figure 13. Generic Processor Interface Read Timing Cycle**

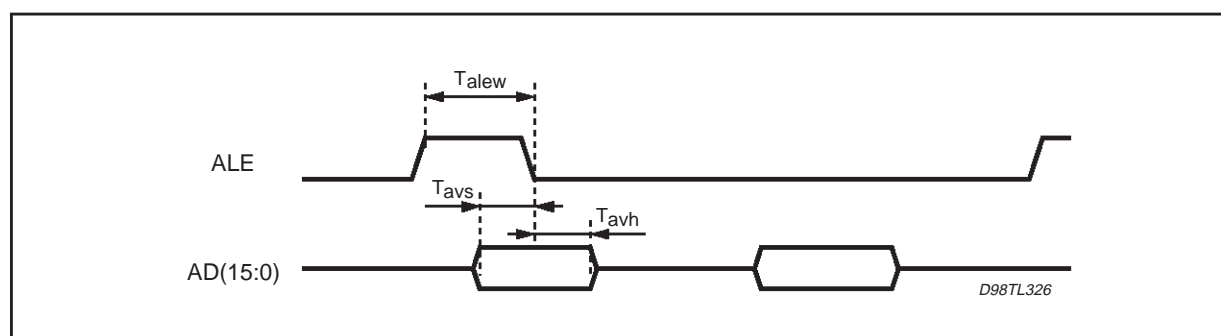


### Generic processor interface Cycle Timing

All AC characteristics are indicated for a 100pF capacitive load.

Symbol	Parameters	Min	Typ	Max	Unit
tr & tf	Rise & Fall time (10% to 90%)			3	ns
Talew	ALE pulse width	12			ns
Tavs	Address Valid setup time	10			ns
Tavh	Address Valid Hold time	10			ns
Tale2cs	ALE to CSB	0			ns
Tale2Z	ALE to high Z state of address bus			50	ns
Tcs2rdy	CSB to RDYB asserted			60	ns
Tcsre	Access Time			900	μs
Tcs2wr	CSB to WRB	0			ns
Twr2d	WRB to data			15	ns
Trdy2wr	RDYB to WRB	0			ns
Tdvs	data setup time	10			ns
Tdvh	data hold time	1/2Tmclk		Tmclk	ns
Twr2cs	WRB to CSB	-10			ns
Tcs2rd	CSB to RDB	0			ns
Trdy2rd	RDY to RDB	0			ns
Trd2cs	RDB to CSB	-10			ns
Tmclk	Master clock Timing				

Figure 14. Waveforms



### Generic Processor Interface Pins and Functional Description

Name	Type	Function
AD[0..15]	I/O	Multiplexed address / data bus
ALE	I	Address Latch Enable
RDB	I	Read cycle indication
WRB	I	Write cycle indication
CSB	I	Chip Select
RDYB	OZ	Bus cycle ready indication
INTB	O	Interrupt

#### ■ Digital interface ATM or serial

Digital Interface for data to the loop before modulation and from the loop after demodulation.

This interface collects cells (from the cell based func-

tion module) or a byte stream (from the deframer). Cells are stored in a fifo, 2 interfaces sub-modules can extract data from the fifo. Byte streams are dumped on the bitstream interface (with no fifo).

3 kinds of interface are allowed

- Utopia level 1
- Utopia level 2
- Bitstream based on a proprietary exchange

The interface selection is programmed by writing the Utopia PHY address register.

Only one interface can be enabled in a ST60135 configuration.

Utopia level 1 supports only one PHY device. Utopia level 2 supports multi-PHY devices (See Utopia level2 specifications)

The Utopia level 2 supports point to multipoint configurations by introducing an addressing capability and by making distinction between polling and selecting a device.

Figure 15. Receive Interface

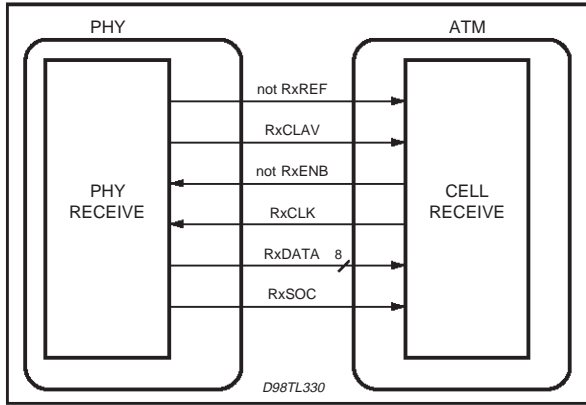
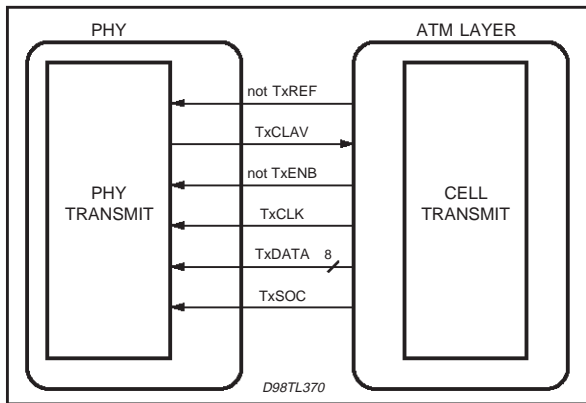


Figure 16. Transmit Interface



Utopia level 1 Interface

The ATM forum takes the ATM layer chip as a reference. It defines the direction from ATM to physical layer as the Transmit direction. The direction from physical layer to ATM is the Receive direction. Figures 15 & 16 show the interconnection between ATM and PHY layer devices, the optional signals are not supported and not shown.

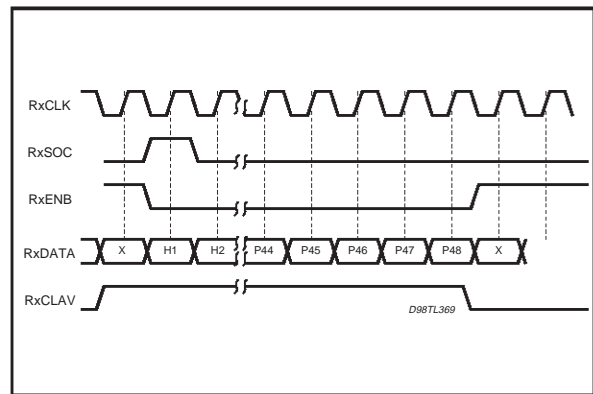
The Utopia interface transfers one byte in a single clock cycle, as a result cells are transformed in 53 clock cycles.

Both transmit and receive are synchronized on clocks generated by the ATM layer chip, and no specific relationship between receive and transmit clocks is required.

In this mode, the STLC60135 can only support one data flow : either interleaved or fast .

The FLOW\_SEL bit in the Utopia PHY address register (0xC44) selects between either the slow (bit13 = 0) or the fast data flow (bit13 = 1).

Figure 17. Timing (Utopia 1 Receive Interface)



Pin Description

Name	Type	Meaning	Usage	Remark
RxCLav	O	Receive Cell available	Signals to the ATM chip that the STLC60135 has a cell ready for transfer	Remains active for the entire cell transfer
RxEnb*	I	Receive Enable	Signals to the STLC60135 that the ATM chip will sample and accept data during next clock cycle	RxData and RxSOC could be tri-state when RxEnb* is inactive (high). Active low signal
RxCk	I	Receive Byte Clock	Gives the timing signal for the transfer, generated by ATM layer chip.	
RxDat	O	Receive Data (8bits)	ATM cell data, from STLC60135 chip to ATM chip, byte wide. Rx Data [7] is the MSB.	
RxSOC	O	Receive Start Cell	Identifies the cell boundary on RxData	Indicate to the ATM layer chip that RxData contains the first valid byte of a cell.
RxRef *	O	Reference Clock	8 kHz clock transported over the network	Active low signal

\*Active low signal



When RxEnb is asserted, the STLC60135 reads data from its internal fifo and presents it on RxData and RxSOC on each low-to-high transition of RxClk, ie the ATM layer chip samples all RxData and RxSOC on the rising edge of RxSOC on the rising edge of RxClk.

tion of RxClk, ie the ATM layer chip samples all RxData and RxSOC on the rising edge of RxSOC on the rising edge of RxClk.

**Pin Description**

Name	Type	Meaning	Usage	Remark
TxClav	O	Transmit Cell available	Signals to the ATM chip that the physical layer chip is ready to accept a complete cell	Remains active for the entire cell transfer
TxEnb*	I	Transmit Enable	Signals to the STLC60135 that TxData and TxSOC are valid	
TxCk	I	Transmit Byte Clock	Gives the timing signal for the transfer, generated by ATM layer chip.	
TxData	I	Transmit Data (8bits)	ATM cell data, from ATM layer chip to STLC60135, byte wide. TxData [7] is the MSB.	
TxSOC	I	Transmit Start of Cell	Identifies the cell boundary on TxData	TxData contains the first valid byte of the cell.
TxRef *	I	Reference Clock	8kHz clock from the ATM layer chip	

\*Active low signal

The STLC60135 samples TxData and TxSOC signals on the rising edge of TxClk, if TxEnb is asserted.

**RxData, RxSOC, RxClav AC electrical characteristics**

**TxCk, RxClk, AC electrical characteristics**

Symbol	Parameters	Min	Max	Unit
F	Clock frequency	1.5	25	MHz
Tc	Clock duty cycle	40	60	%
Tj	Clock peak to peak jitter		5	%
Trf	Clock rise fall time		4	ns
L	Load		100	pF

Symbol	Parameters	Min	Max	Unit
T7	Input set-up time to TxClk	10		ns
T8	Hold time to Tx Clk	1		ns
T9	Signal going low impedance to RxClk	10		ns
T10	Signal going High impedance to RxClk	0		ns
T11	Signal going low impedance to RxClk	1		ns
T12	Signal going High impedance to RxClk	1		ns
L	Load		100	pF

**TxData, TxSOC, AC electrical characteristics**

Symbol	Parameters	Min	Max	Unit
T5	Input set-up time to TxClk	10		ns
T6	Hold time to TxClk	1		ns
L	Load		100	pF

**Figure 18. Timing (Utopia 1 Transmit Interface)**

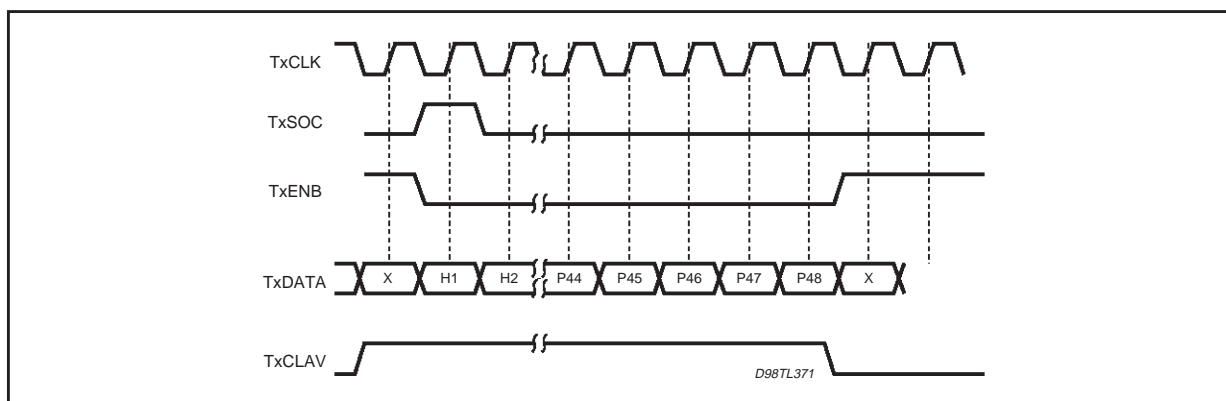
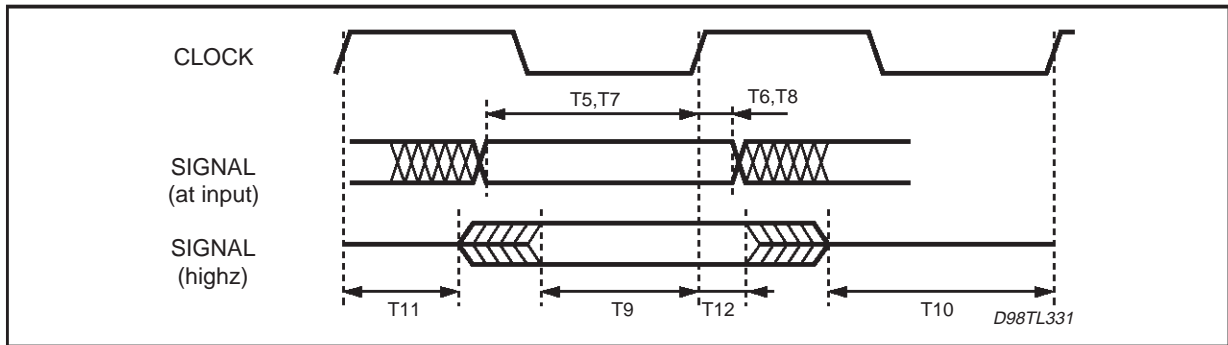


Figure 19. Timing Specification (Utopia 1)



**DIGITAL INTERFACE**

**Utopia Level 2 Interface**

The ATM forum takes the ATM layer chip as a reference. It defines the direction from ATM to physical layer as the Transmit direction. The direction from physical layer to ATM is the Receive direction. Figure 20 shows the interconnection between ATM and PHY layer devices, the optional signals are not supported and not shown.

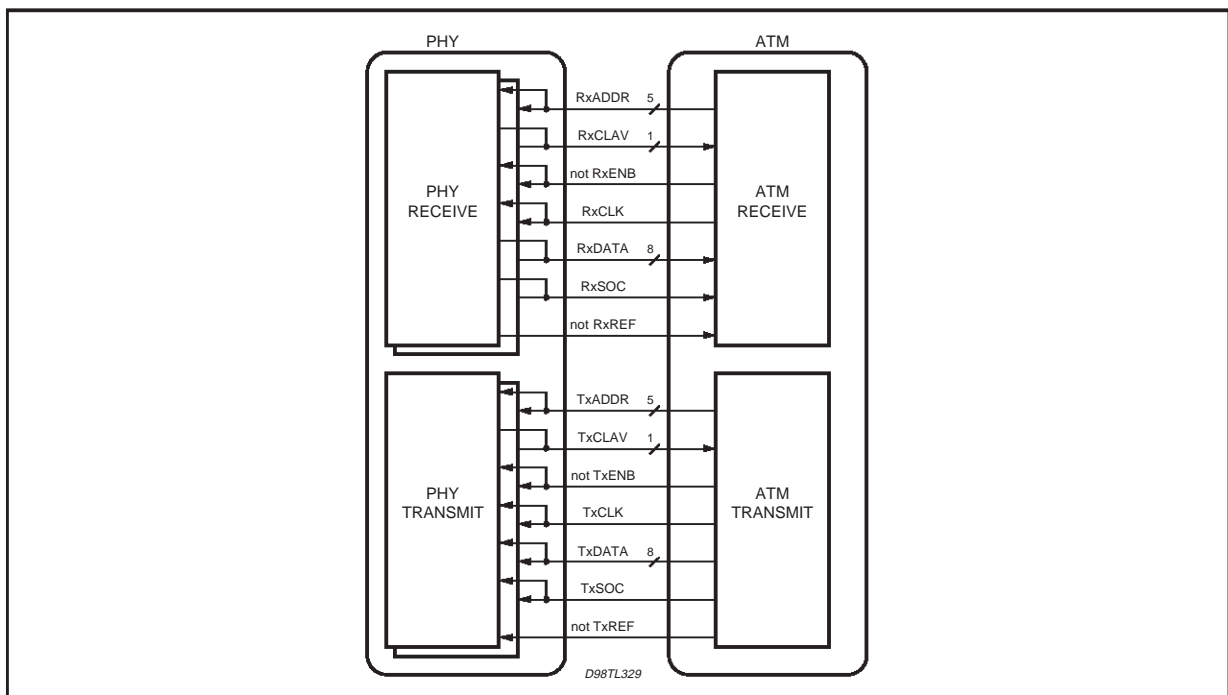
The UTOPIA interface transfers one byte in a single clock cycle, as a result cells are transferred in 53 clock cycles.

Both transmit and receive interfaces are synchronized on clocks generated by the ATM layer chip, and no specific relationship between Receive and Transmit clock is assumed, they must be regarded as mutually asynchronous clocks. Flow

control signals are available to match the bandwidth constraints of the physical layer and the ATM layer. The UTOPIA level 2 supports point to multipoint configurations by introducing on addressing capability and by making a distinction between polling and selecting a device:

- the ATM chip polls a specific physical layer chip by putting its address on the address bus when the Enb line is asserted. The addressed physical layer answers the next cycle via a Clav line reflecting its status at that time.
- the ATM chip selects a specific physical layer by putting its address on the address bus when the Enb line is deasserted and asserting the Enb line on the next cycle. The addressed physical layer chip will be the target or source of the next cell transfer.

Figure 20. Signal at Utopia Level 2 Interface





### Utopia Level 2 Signals

The physical chip sends cell data towards the ATM layer chip.

The ATM layer chip polls the status of the fifo of the physical layer chip.

The cell exchange proceeds like:

- a) The physical layer chip signals the availability of a cell by asserting RxClav when polled by the ATM chip.
- b) The ATM chips selects a physical layer chip, then starts the transfer by asserting RxEnb\*.
- c) If the physical layer chip has data to send, it puts them on the RxData line the cycle after it sampled RxEnb\* active. It also advances the offset in the cell. If the data transferred is the first byte of a cell, RxSOC is 1b at the time of the data transfer, 0b otherwise.
- d) The ATM chip accepts the data when they are available. If RxSOC was 1b during the transfer, it resets its internal offset pointer to the value 1, otherwise it advances the offset in the cell.

### STLC60135 Utopia Level 2 MPHY Operation

Utopia level 2 MPHY operation can be done by various interface schemes. The STLC60135 supports only the required mode, this mode is referred to as operation with 1 TxClav and 1 RxClav.

### PHY Device Identification

The STLC60135 holds 2 PHY layer Utopia parts, one is dedicated to the fast data channel, the other one to the interleaved data channel. The associated PHY address is specified by the PHY\_ADDR\_x fields in the Utopia PHY address register. Beware that an incorrect address configuration may lead to bus conflicts. A feature is defined to disable (tri-state) all outputs of the Utopia interface. It is enabled by the TRI\_STATE\_EN bit in the Rx\_interface control register.

In the case of multi-PHY, the RxClav signal of each STLC60135 is connected to one dedicate inputs of ATM layer chip, i.e. no tri-state property is needed for RxClav.

### Pin Description Utopia 2 (Receive Interface)

Name	Type	Meaning	Usage	Remark
RxClav	O	Receive Cell available	Signals to the ATM chip that the STLC60135 has a cell ready for transfer	Remains active for the entire cell transfer
RxEnb*	I	Receive Enable	Signals to the physical layer that the ATM chip will sample and accept data during next clock cycle	RxData and RxSOC could be tri-state when RxEnb* is inactive (high)
RxCk	I	Receive Byte Clock	Gives the timing signal for the transfer, generated by ATM layer chip.	
RxData	O	Receive Data (8 bits)	ATM cell data, from physical layer chip to ATM chip, byte wide.	
RxSOC	O	Receive Start Cell	Identifies the cell boundary on RxData	Indicate to the ATM layer chip that RxData contains the first valid byte of a cell.
RxAddr	I	Receive Address (5 bits)	Use to select the port that will be active or polled	
RxRef *	O	Reference Clock	8kHz clock transported over the network	

\*Active low signal

**Pin Description Utopia 2 (Transmit interface)**

Name	Type	Meaning	Usage	Remark
TxClav	O	Transmit Cell available	Signals to the ATM chip that the physical layer chip is ready to accept a cell	Remains active for the entire cell transfer
TxEnb*	I	Transmit Enable	Signals to the physical layer that TxData and TxSOC are valid	
TxCk	I	Transmit Byte Clock	Gives the timing signal for the transfer, generated by ATM layer chip.	
TxData	I	Transmit Data (8 bits)	ATM cell data, to physical layer chip to ATM chip, byte wide.	
TxSOC	I	Transmit Start of Cell	Identifies the cell boundary on TxData	
TxAddr	I	Transmit Address (5 bits)	Use to select the port that will be active or polled	
TxRef *	I	Reference Clock	8kHz clock from the ATM layer chip	

\*Active low signal

**BitStream Interface**

The Bitstream interface is a proprietary point to point interface. The STLC60135 is the bus master of the interface. The interface is synchronous, a common clock is used.

**SLAP (Synchronous Link Access Protocol) Interface**

The SLAP interface is a point to point bitstream interface. The STLC60135 is the bus master of the interface.

The interface is synchronous, a common clock (SLAP\_CLOCK) is used. The basic idea is illustrated in Figure 20.

The SLAP interface dumps the data of the fast and interleaved channels on 2 separate sub interfaces.

The data flow from the SLAP interface must be

enabled by the Transceiver Controller. A disabled cell interface does not dump data on its interface.

**Receive SLAP Interface**

The interface signals use 2 signal types: (refer to fig. 22)

- SLR\_DATA [1:0]: data pins, a byte is transferred in 4 cycles of 2 bits. The msb are transmitted first, odd bits are asserted on SRL\_DATA [1].

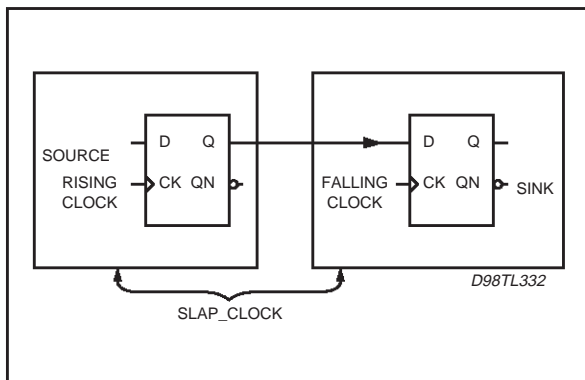
- SLR\_VAL: indicates the data transfer and the byte boundary

- SLR\_FRAME: indicates the start of a super-frame

Notice 2 SLAP interfaces are supported, one for the fast data flow, the other one for the interleaved data flow.

The logic timing diagram is shown in figure 23.

**Figure 21. Common Clock Data Transfer**



**Figure 22. Receive Path, SLAP Interface**

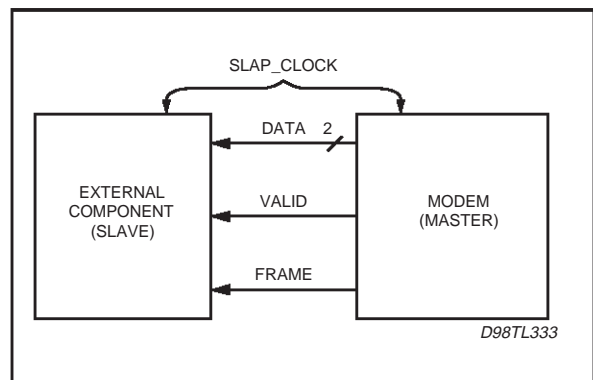
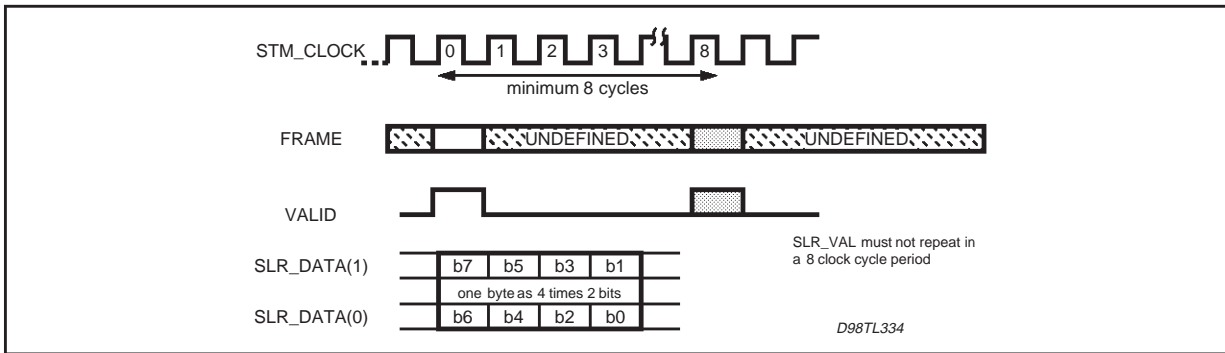


Figure 23. Receive SLAP Interface Timing



The implementation must guarantee that all active SLR\_Valid signals must be separated by at least 8 clock cycles.

Refer to Figure 23. The SLR\_FRAME signals are asserted when the first pair of bits of a frame are transferred. For the fast channel a frame is defined as a superframe timebase.

For the interleaved channel the frame is defined by a timebase period of 4 superframes. Both timebases are synchronized to the data flow.

**Transmit SLAP Interface**

The Transmit interface uses the following signals (refer to Figure 24)

- SLT\_REQ: byte request
- SLT\_FRAME: start of frame indication

Figure 24. Interface Towards PHY Layer

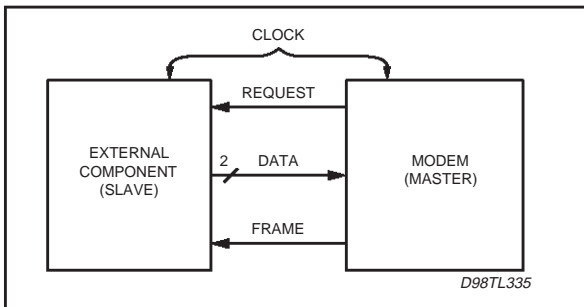
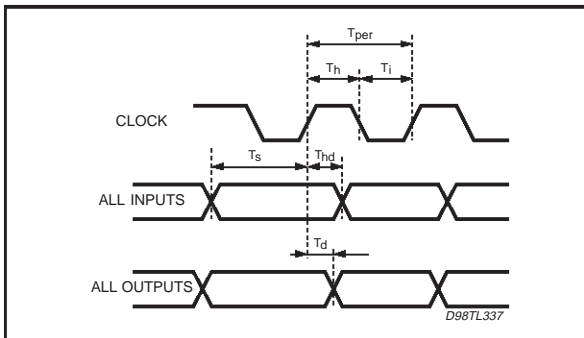


Figure 26. Interface Timing



- SLT\_DATA [1:0] data pins, a byte is transferred 2 bits at the time in 4 successive clock cycles. MSB first, odd bits on SLT\_DATA [1]

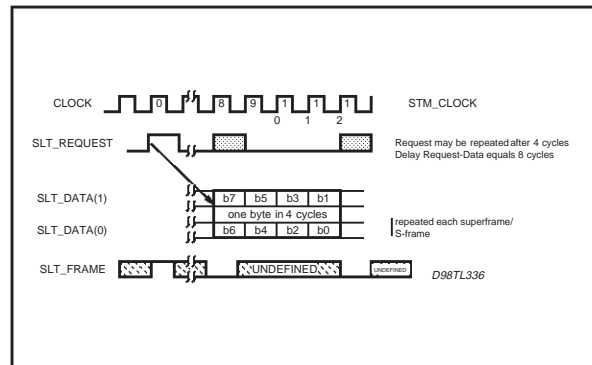
The logical timing diagram is shown in Figure 25. The delay between Request and the associated data byte is defined as 8 cycles.

The SLT\_FRAME signals are asserted when the first pair of bits of a frame are transferred. For the fast channel a frame is defined as a superframe timebase.

For the interleaved channel the frame is defined by a timebase period of 4 superframes.

Both timebases are synchronized to the data flow and guarantee that the frame indication is asserted when the first bits of the first DMT symbol are transferred.

Figure 25. Transmit SLAP Interface Timing Diagram



SLAP INTERFACE, AC Electrical Characteristics

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Tper	Clock Period	refer to MCLK				ns
Th	Clock High		11			ns
Tl	Clock Low		11			ns
Ts	Setup		3			ns
Thd	Hold		2			ns
Td	Data Delay	20pF load	3		6	ns

■ Analog Front End Control Interface

The Analog Front End Interface is designed to be connected to the STLC60134 Analog Front End component.

Transmit Interface

The 16 bit words are multiplexed on 4 AFTXD output signals. As a result 4 cycles are needed to transfer 1 word. Refer to table 1 for the bit / pin allocation for the 4 cycles. The first of 4 cycles is identified by the CLWD signal. Refer to Figure 26.

The STLC60135 fetches the 16 bit word to be multiplexed on AFTXD from the Tx Digital Front-End module.

Receive Interface

The 16 bit receive word is multiplexed on 4 AFRXD input signals. As a result 4 cycles are needed to transfer 1 word. Refer to Table 2 for the bit / pin allocation for the 4 cycles. The first of 4 cycles is identified by the CLWD must repeat after 4 MCLK cycles.

Figure 27. TransmittWord Timing Diagram

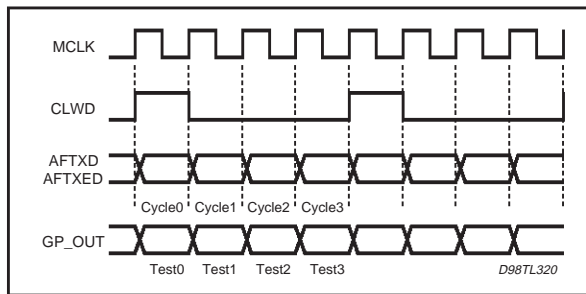


Table 1: Transmitted Bits Assigned to Signal / Time Slot

	Cycle 0	Cycle 1	Cycle 2	Cycle 3
AFTXD[0]	b0	b4	b8	b12
AFTXD[1]	b1	b5	b9	b13
AFTXD[2]	b2	b6	b10	b14
AFTXD[3]	b3	b7	b11	b15
GP_OUT	t0	t1	t2	t3

Figure 28. Receive Word Timing Diagram

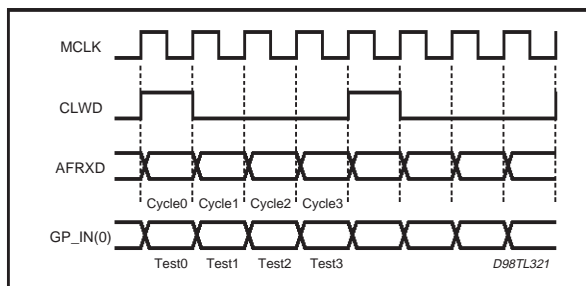


Table 2: Transmitted Bits Assigned to Signal / Time Slot

	Cycle 0	Cycle 1	Cycle 2	Cycle 3
AFRXD[0]	b0	b4	b8	b12
AFRXD[1]	b1	b5	b9	b13
AFRXD[2]	b2	b6	b10	b14
AFRXD[3]	b3	b7	b11	b15
GP_IN	t0	t1	t2	t3

Figure 29. Transmit Interface

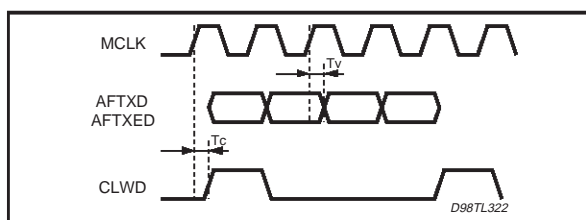
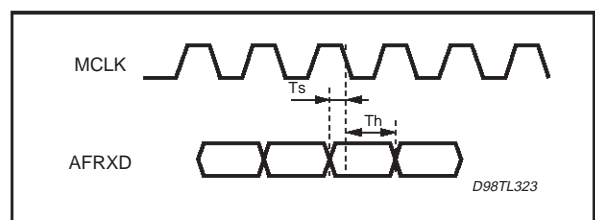


Figure 30. Receive Interface



**Table 3: Master Clock (MCLK) AC Electrical Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
F	Clock Frequency			35.328		MHz
Tper	Clock Period			28.3		ns
Th	Clock Duty Cycle		40		60	%

**Table 4: AFTXD, AFTXED, CLWD AC Electrical Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Tv	Data Valid Time		0		10	ns
Tc	Data Valid Time		0		10	ns

**Table 5: AFRXD AC Electrical Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Ts	Data setup Time		5			ns
Th	Data hold Time		5			ns

**Tests, Clock, JTAG Interface**

- Mclk: Master Clock (35.328MHz) generated by VCXO

- ATM receive interface, asynchronous clock generated by Utopia Master

- ATM transmit interface, asynchronous clock generated by Utopia Master

- ATC clock (Pclk): external asynchronous clock (synchronous with ATC in case of i960 specific interface)

JTAG TP interface: Standard Test Access Port, Used with the boundary scan for chip and board testing.

This JTAG TAP interface consists in 5 signals:

TDI, TDO, TCK & TMS.

TSRTB: Test Reset, reset the TAP controller. TRSTB is an active low signal.

**Table 6: Boundary Scan Chain Sequence**

Sequence Number	Mnemonic	Pin	BS Type
2	AD_0		B
3	AD_1		B
4	AD_2		B
6	AD_3		B
7	AD_4		B
9	AD_5		B
10	AD_6		B
12	AD_7		B
13	AD_8		B
14	AD_9		B
16	AD_10		B

17	AD_11		B
19	AD_12		B
21	PCLK		I
23	AD_13		B
24	AD_14		B
25	AD_15		B
27	BE1		I
28	ALE		C
30	CSB		I
31	WR_RDB		I
32	RDYB		O
33	OBC_TYPE		I
34	INTB		O
35	RESETB		I
38	U_RxData_0		B
39	U_RxData_1		B
41	U_RxData_2		B
42	U_RxData_3		B
44	U_RxData_4		B
45	U_RxData_5		B
46	VSS		
47	U_RxData_6		B
48	U_RxData_7		B
50	U_RxADDR_0		I
51	U_RxADDR_1		I
52	U_RxADDR_2		I
53	U_RxADDR_3		I
55	U_RxADDR_4		I
56	GP_IN_0		i
58	GP_IN_1		I
60	U_RxRefB		O

Table 6: (continued)

Sequence Number	Mnemonic	Pin	BS Type
61	U_TxRefB		I
63	U_RxCLK		
64	U_RxSOC		
65	U_RxCLAV		
66	U_RxENBB		
68	U_TxCLK		
69	U_TxSOC		
70	U_TxCLAV		
71	U_TxENBB		
74	U_TxData_7		I
75	U_TxData_6		I
77	U_TxData_5		I
78	U_TxData_4		I
79	U_TxData_3		I
80	U_TxData_2		I
82	U_TxData_1		I
83	U_TxData_0		I
84	U_TxADDR_4		I
85	U_TxADDR_3		I
87	U_TxADDR_2		I
88	U_TxADDR_1		I
89	U_TxADDR_0		I
90	SLR_FRAME_F		
92	SLR_FRAME_S		
93	SLR_DATA_S_1		
94	SLR_DATA_S_0		
96	SLR_DATA_S		
97	SLR_DATA_F_1		
98	SLR_DATA_F_0		
99	SLR_VAL_F		
100	SLAP_CLOCK		
101	SLT_FRAME_F		
103	SLT_DATA_F_1		
104	SLT_DATA_F_0		
105	SLT_DATA_S_1		
106	SLT_DATA_S_0		
107	SLT_REQ_F		
110	SLT_REQ_S		
111	SLT_FRAME_S		
112	TDI		
113	TDO		
114	TMS		
116	TCK		
118	TRSTB		
119	TESTSE		none
120	GP_OUT		O

121	PDOWN		O
123	AFRXD_0		I
124	AFRXD_1		I
125	AFRXD_2		I
126	AFRXD_3		I
128	CLWD	1	I
129	MCLK	1	C
130	CTRLDATA	1	O
132	AFTXD_0		O
133	AFTXD_0		O
135	AFTXD_0		O
136	AFTXD_0		O
138	IDDq		none
139	AFTXD_0		O
140	AFTXD_1		O
142	AFTXD_0		O
143	AFTXD_1		O

**General purpose I/O register**

2 general Purpose Register (0x040)

Field	Type	Position bits	Length	Function
GP_IN	R	[0,1]	2	Sampled level on pins GP_IN
GP_OUT	RW	[2]	1	Output level on pins GP_OUT

bits from 3 to 15 are reserved

**Reset Initialization**

The STLC60135 supports two reset modes:

- A 'hardware' reset is activated by the RESETB pin (active low). A hard reset occurs when a low input value is detected at the RESETB input. The low level must be applied for at least 1ms to guarantee a correct reset operation. All clocks and power supplies must be stable for 200ns prior to the rising edge of the RESETB signal.
- 'Soft' reset activated by the controller write access to a soft reset configuration bit. The reset process takes less than 10000 MCLK clock cycles.

**ELECTRICAL SPECIFICATIONS**

**Generic**

The values presented in the following table apply for all inputs and/or outputs unless specified otherwise. Specifically they are not influenced by the choice between CMOS or TTL levels.



**DC Electrical Characteristics**

(All voltages are referenced to VSS, unless otherwise specified, positive current is towards the device)

**IO Buffers Generic DC Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = V <sub>SS</sub> , V <sub>DD</sub> no pull up / pull down	-1		1	mA
I <sub>OZ</sub>	Tristate Leakage Current	V <sub>IN</sub> = V <sub>SS</sub> , V <sub>DD</sub> no pull up / pull down	-1		1	mA
I <sub>PU</sub>	Pull up Current	V <sub>IN</sub> = V <sub>SS</sub>	-25	-66	-125	mA
I <sub>PD</sub>	Pull Down Current	V <sub>IN</sub> = V <sub>DD</sub>	25	66	125	mA
R <sub>PU</sub>	Pull up Resistance	V <sub>IN</sub> = V <sub>SS</sub>		50		K $\Omega$
R <sub>PD</sub>	Pull Down Resistance	V <sub>IN</sub> = V <sub>DD</sub>		50		K $\Omega$

**IO Buffers Dynamic DC Characteristics**

Important for transient but measured at (near) DC

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
C <sub>IN</sub>	Input Capacitance	@f = 1MHz		5		pF
di/dt	Current Derivative	8mA driver, slew rate control		23.5		mA/ns
		8mA driver, no slew rate control		89	-125	mA/ns
I <sub>peak</sub>	Peak Current	8mA driver, slew rate control		85		mA
		8mA driver, no slew rate control		100		mA
C <sub>OUT</sub>	Output Capacitance (also bidirectional and tristate drivers)	@f = 1MHz		7		pF

**Input / Output CMOS Generic Characteristics**

The values presented in the following table apply for all CMOS inputs and/or outputs unless specified otherwise.

**CMOS IO Buffers Generic Characteristics**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V <sub>IL</sub>	Low Level Input Voltage				0.2 x V <sub>DD</sub>	V
V <sub>IH</sub>	High Level Input Voltage		0.8 x V <sub>DD</sub>			V
V <sub>HY</sub>	Schmitt trigger hysteresis	slow edge < 1V/ms, only for SCHMITx	0.8			V
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OUT</sub> = XmA*			0.4	V
V <sub>OH</sub>	High Level Output Voltage	I <sub>OUT</sub> = XmA*	0.85 x V <sub>DD</sub>			V

\* The reference current is dependent on the exact buffer chosen and is a part of the buffer name. The available values are 2, 4 and 8mA.

**Input/ Output TTL Generic Characteristics**

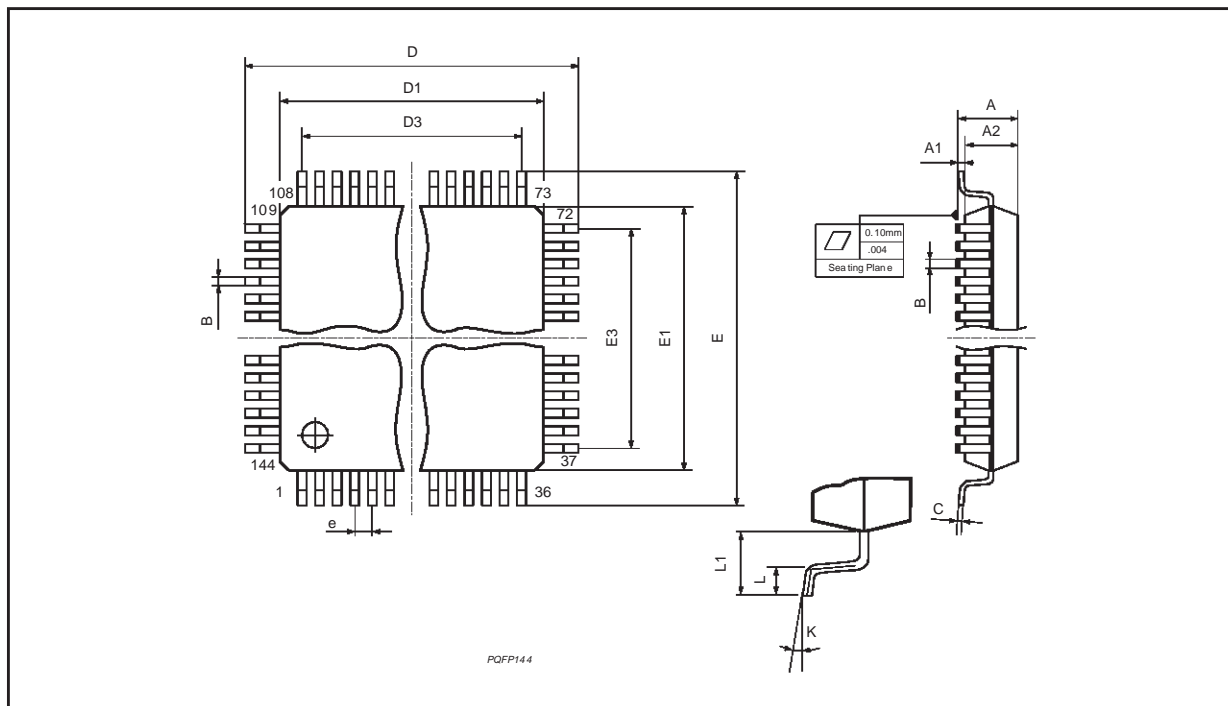
The values presented in the following table apply for all TTL inputs and/or outputs unless specified otherwise

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V <sub>IL</sub>	Low Level Input Voltage				0.8	V
V <sub>IH</sub>	High Level Input Voltage		2.0			V
V <sub>ILHY</sub>	Low Level Threshold, falling	slow edge < 1V/ms	0.9		1.35	V
V <sub>IHHY</sub>	High Level Threshold, rising	slow edge < 1V/ms	1.3		1.9	V
V <sub>HY</sub>	Schmitt Trigger Hysteresis	slow edge < 1V/ms	0.4		0.7	V
V <sub>OL</sub>	Low Level Output Voltage	I <sub>OUT</sub> = XmA*			0.4	V
V <sub>OH</sub>	High Level Output Voltage	I <sub>OUT</sub> = XmA*	2.4			V

\* The reference current is dependent on the exact buffer chosen and is a part of the buffer name. The available values are 2, 4 and 8mA.

PQFP144 PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			4.07			0.160
A1	0.25			0.010		
A2	3.17	3.42	3.67	0.125	0.135	0.144
B	0.22		0.38	0.009		0.015
C	0.13		0.23	0.005		0.009
D	30.95	31.20	31.45	1.219	1.228	1.238
D1	27.90	28.00	28.10	1.098	1.102	1.106
D3		22.75			0.896	
e		0.65			0.026	
E	30.95	31.20	31.45	1.219	1.228	1.238
E1	27.90	28.00	28.10	1.098	1.102	1.106
E3		22.75			0.896	
L	0.65	0.80	0.95	0.026	0.031	0.037
L1		1.60			0.063	
K	0°(min.), 7°(max.)					





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